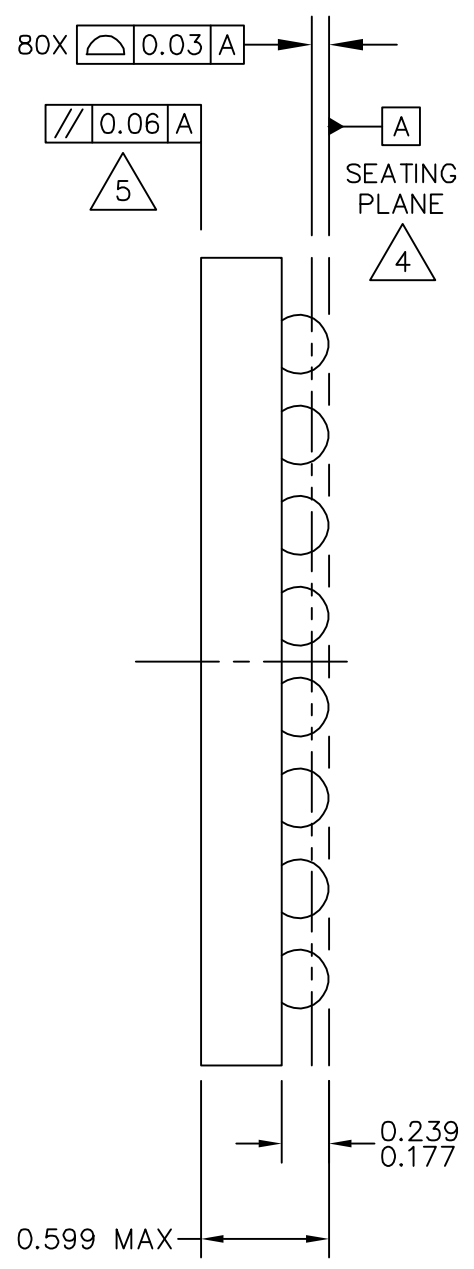
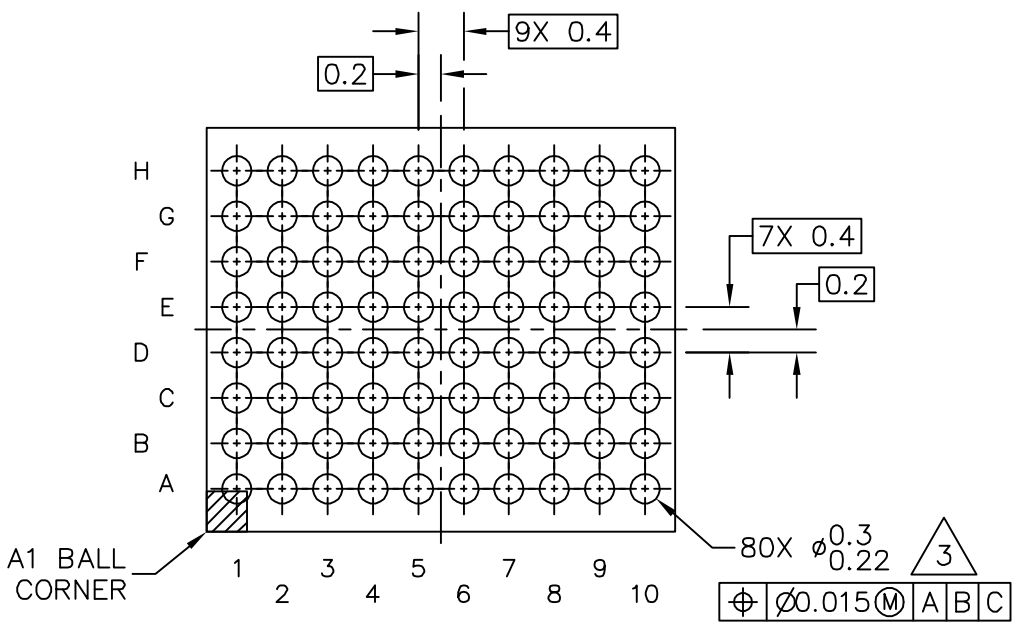


TOP VIEW



VIEW D-D



BOTTOM VIEW

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TITLE: WLCSP, 4.13 X 3.56 X 0.564 PKG, 0.4 MM PITCH, 80 I/O	DOCUMENT NO: 98ASA00710D	REV: A
	STANDARD: NON-JEDEC	
	SOT1783-1	12 JAN 2016



NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.

2. DIMENSIONING AND TOLERANCING PER ASME Y14.5–2009.

3. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM A.

4. DATUM A, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.

5. PARALLELISM MEASUREMENT SHALL EXCLUDE ANY EFFECT OF MARK ON TOP SURFACE OF PACKAGE.

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TITLE: WLCSP, 4.13 X 3.56 X 0.564 PKG, 0.4 MM PITCH, 80 I/O		DOCUMENT NO: 98ASA00710D	REV: A
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